

Title (en)
WAFERBOARD LUMBER

Publication
EP 0259069 A3 19890215 (EN)

Application
EP 87307378 A 19870820

Priority
CA 517415 A 19860903

Abstract (en)
[origin: EP0259069A2] Substitute lumber pieces having strengths and densities substantially equivalent to lumber are cut from single layer panels (18) of over about 1 and normally less than 4 inch thickness made from wood wafers. The wafers are oriented with their lengths having a mean deviation to the longitudinal length of the panel measured in the major plane of the panel in the range of 0 to 10 degrees and a mean deviation measured in a minimum longitudinal plane perpendicular to the major plane from 0 to about 5 degrees and have an average effective length of at least 8 inches (200 mm), and preferably an average thickness less than 0.15 inches (4 mm) and a width of at least 0.25 inches (6 mm). Lumber is made by cutting the panel longitudinally. Preferably the panels are formed to have a substantially uniform density profile throughout their thicknesses.

IPC 1-7
B27N 3/04

IPC 8 full level
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CPC (source: EP)
B27B 1/00 (2013.01); **B27N 3/04** (2013.01); **B27N 3/143** (2013.01)

Citation (search report)
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• [A] PATENT ABSTRACTS OF JAPAN, vol. 5, no. 39 (M-59)[711], 14th March 1981; & JP-A-55 164 141 (MASAO TAKAHASHI) 20-12-1980

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